INSTRUCTIONS FOR ASSEMBLING AND MAILING YOUR APPLICATION PACKAGES FOR NON-OSCAR JUDGES
Revised April 2006

ASSEMBLING YOUR APPLICATION PACKAGE

Your application package for a judicial clerkship should be assembled as follows, from top to bottom:

- cover letter (on quality bond paper);
- resume (on quality bond paper);
- transcript(s) (on regular copier paper);
- writing sample, if requested (on regular copier paper);
- sealed letters of reference

Your cover letter should inform the judge that confidential recommendation letters are included in your package, and should refer to the writers by name. If faculty letters or letters from others will be mailed directly to the judge, that information (including the name(s) of the writer(s)) should also be included in your cover letter.

SENDING YOUR APPLICATION PACKAGE

For Federal Judges Following the Federal Law Clerk Hiring Plan
The first date on which you may mail or hand-deliver applications for federal judicial clerkships with judges following the Federal Law Clerk Hiring Plan is the day after Labor Day.

For Federal Judges NOT Following the Federal Law Clerk Hiring Plan
Your applications to judges not following the Federal Law Clerk Hiring Plan should be mailed at whatever time the judge indicates he or she is accepting applications.

For State Judges and Administrative Law Judges (ALJs)
Your applications to state court judges and ALJs should be mailed at whatever time the judge indicates he or she is accepting applications.